Integrated Silicon Pressure Sensor
On-Chip Signal Conditioned, Temperature Compensated and Calibrated

The MP3V5010 series piezoresistive transducers are state-of-the-art monolithic silicon pressure sensors designed for a wide range of applications, but particularly those employing a microcontroller or microprocessor with A/D inputs. This transducer combines advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure.

Features

• 5.0% Maximum Error Over 0° to 85°C
• Ideally Suited for Microprocessor or Microcontroller-Based Systems
• Temperature Compensated Over –40° to +125°C
• Thermoplastic (PPS) Surface Mount Package
• Patented Silicon Shear Stress Strain Gauge
• Available in Differential and Gauge Configurations

ORDERING INFORMATION

<table>
<thead>
<tr>
<th>Device Name</th>
<th>Package Options</th>
<th>Case No.</th>
<th># of Ports</th>
<th>Pressure Type</th>
<th>Device Marking</th>
</tr>
</thead>
<tbody>
<tr>
<td>MP3V5010GC6U</td>
<td>Rails</td>
<td>482A</td>
<td>•</td>
<td>None</td>
<td>MP3V5010G</td>
</tr>
<tr>
<td>MP3V5010GC6T1</td>
<td>Tape &amp; Reel</td>
<td>482A</td>
<td>•</td>
<td>Single, Dual,</td>
<td>MP3V5010G</td>
</tr>
<tr>
<td>MP3V5010GP</td>
<td>Trays</td>
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<td>•</td>
<td>Dual,</td>
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</tr>
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<td>MP3V5010GVP</td>
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<td>•</td>
<td></td>
<td>MP3V5010GVP</td>
</tr>
</tbody>
</table>

Application Examples

• Hospital Beds
• HVAC
• Respiratory Systems
• Process Control

MP3V5010 Series
0 to 10 kPa (0 to 1.45 psi)
0.1 to 3.1 V Output

SMALL OUTLINE PACKAGE

MP3V5010GC6U/C6T1 CASE 482A-01
MP3V5010GP CASE 1369-01
MP3V5010DP CASE 1351-01
MP3V5010GVP CASE 1368-01

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Operating Characteristics

Table 1. Operating Characteristics ($V_S = 3.0\ V_{dc}$, $T_A = 25^\circ C$ unless otherwise noted, $P_1 > P_2$. Decoupling circuit shown in Figure 3 required to meet specification.)

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Symbol</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
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</thead>
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<tr>
<td>Pressure Range</td>
<td>$P_{OP}$</td>
<td>0</td>
<td>—</td>
<td>10</td>
<td>kPa</td>
</tr>
<tr>
<td>Supply Voltage</td>
<td>$V_S$</td>
<td>2.7</td>
<td>3.0</td>
<td>3.3</td>
<td>Vdc</td>
</tr>
<tr>
<td>Supply Current</td>
<td>$I_o$</td>
<td>—</td>
<td>7.0</td>
<td>10</td>
<td>mAdc</td>
</tr>
<tr>
<td>Minimum Pressure Offset(3)</td>
<td>$V_{off}$</td>
<td>0.1</td>
<td>0.24</td>
<td>0.38</td>
<td>Vdc</td>
</tr>
<tr>
<td>Full Scale Output</td>
<td>$V_{FSO}$</td>
<td>2.81</td>
<td>2.94</td>
<td>3.08</td>
<td>Vdc</td>
</tr>
<tr>
<td>Full Scale Span</td>
<td>$V_{FSS}$</td>
<td>—</td>
<td>2.7</td>
<td>—</td>
<td>Vdc</td>
</tr>
<tr>
<td>Accuracy(6)</td>
<td></td>
<td>—</td>
<td>—</td>
<td>±5.0</td>
<td>%$V_{FSS}$</td>
</tr>
<tr>
<td>Sensitivity</td>
<td>$V/P$</td>
<td>—</td>
<td>270</td>
<td>—</td>
<td>mV/kPa</td>
</tr>
<tr>
<td>Response Time(7)</td>
<td>$t_R$</td>
<td>—</td>
<td>1.0</td>
<td>—</td>
<td>ms</td>
</tr>
<tr>
<td>Output Source Current at Full Scale Output</td>
<td>$I_{O+}$</td>
<td>—</td>
<td>0.1</td>
<td>—</td>
<td>mAdc</td>
</tr>
<tr>
<td>Warm-Up Time(8)</td>
<td></td>
<td>—</td>
<td>20</td>
<td>—</td>
<td>ms</td>
</tr>
<tr>
<td>Offset Stability(9)</td>
<td></td>
<td>—</td>
<td>±0.5</td>
<td>—</td>
<td>%$V_{FSS}$</td>
</tr>
</tbody>
</table>

1. 1.0 kPa (kiloPascal) equals 0.145 psi.
2. Device is ratiometric within this specified excitation range.
3. Offset ($V_{off}$) is defined as the output voltage at the minimum rated pressure.
4. Full Scale Output ($V_{FSO}$) is defined as the output voltage at the maximum or full rated pressure.
5. Full Scale Span ($V_{FSS}$) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
6. Accuracy (error budget) consists of the following:
   - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
   - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
   - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.
   - $Tc$Span: Output deviation over the temperature range of 0° to 85°C, relative to 25°C.
   - $Tc$Offset: Output deviation with minimum rated pressure applied, over the temperature range of 0° to 85°C, relative to 25°C.
   - Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of $V_{FSS}$, at 25°C.
7. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
8. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.
9. Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.
Maximum Ratings

Table 2. Maximum Ratings\(^{(1)}\)

<table>
<thead>
<tr>
<th>Rating</th>
<th>Symbol</th>
<th>Value</th>
<th>Unit</th>
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<tr>
<td>Maximum Pressure (P1 &gt; P2)</td>
<td>$P_{\text{max}}$</td>
<td>75</td>
<td>kPa</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>$T_{\text{stg}}$</td>
<td>–40 to +125</td>
<td>°C</td>
</tr>
<tr>
<td>Operating Temperature</td>
<td>$T_A$</td>
<td>–40 to +125</td>
<td>°C</td>
</tr>
</tbody>
</table>

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

![Schematic Diagram](image-url)

**Figure 1. Integrated Pressure Sensor Schematic**
ON-CHIP TEMPERATURE COMPENSATION, CALIBRATION AND SIGNAL CONDITIONING

The performance over temperature is achieved by integrating the shear-stress strain gauge, temperature compensation, calibration and signal conditioning circuitry onto a single monolithic chip.

Figure 2 illustrates the Differential or Gauge configuration in the basic chip carrier (Case 482). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm.

The MP3V5010 series pressure sensor operating characteristics, and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 3 shows the recommended decoupling circuit for interfacing the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

Figure 4 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in Figure 3. The output will saturate outside of the specified pressure range.

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**Figure 2. Cross-Sectional Diagram SOP (not to scale)**

**Figure 3. Recommended Power Supply Decoupling and Output Filtering**
(For additional output filtering, please refer to Application Note AN1646.)
Transfer Function

Nominal Transfer Value:

\[ V_{\text{out}} = V_S \times (0.09 \times P + 0.08) \pm \text{Error} \]
\[ V_S = 3.0 \text{ Vdc} \]
TEMP = 0 to 85°C

Temperature Error Band

MP3V5010 SERIES

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<tr>
<th>Temp</th>
<th>Multiplier</th>
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<tr>
<td>−40</td>
<td>3</td>
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<tr>
<td>0 to 85</td>
<td>1</td>
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<tr>
<td>+125</td>
<td>3</td>
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</table>

Temperature Error Factor

NOTE: The Temperature Multiplier is a linear response from 0° to −40°C and from 85° to 125°C.
PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

Freescale designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing fluoro silicone gel which protects the die from harsh media. The pressure sensor is designed to operate with positive differential pressure applied, \( P_1 > P_2 \).

The Pressure (P1) side may be identified by using the following table:

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Case Type</th>
<th>Pressure (P1) Side Identifier</th>
</tr>
</thead>
<tbody>
<tr>
<td>MP3V5010GC6U/C6T1</td>
<td>482A</td>
<td>Side with Port Attached</td>
</tr>
<tr>
<td>MP3V5010GP</td>
<td>1369</td>
<td>Side with Port Attached</td>
</tr>
<tr>
<td>MP3V5010DP</td>
<td>1351</td>
<td>Side with Part Marking</td>
</tr>
<tr>
<td>MP3V5010GVP</td>
<td>1368</td>
<td>Side with Part Marking</td>
</tr>
</tbody>
</table>

MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the surface mount packages must be the correct size to ensure proper solder connection interface between the board and the package. With the correct footprint, the packages will self align when subjected to a solder reflow process. It is always recommended to design boards with a solder mask layer to avoid bridging and shorting between solder pads.

Figure 5. Small Outline Package Footprint
PACKAGE DIMENSIONS

CASE 482A-01
ISSUE A
SMALL OUTLINE PACKAGE

NOTES:
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.
PACKAGE DIMENSIONS

MECHANICAL OUTLINE

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CASE 1368-01

ISSUE C

SMALL OUTLINE PACKAGE
PACKAGE DIMENSIONS

CASE 1368-01
ISSUE C
SMALL OUTLINE PACKAGE

MECHANICAL OUTLINE

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</tbody>
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CASE 1368-01
ISSUE C
SMALL OUTLINE PACKAGE

Downloaded from Arrow.com.
## PACKAGE DIMENSIONS

**NOTES:**

1. CONTROLLING DIMENSION: INCH

⚠️ THIS DIMENSION DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.

⚠️ THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

### STYLE 1

- PIN 1: GND
- PIN 2: +Vout
- PIN 3: Vx
- PIN 4: −Vout
- PIN 5: N/C
- PIN 6: N/C
- PIN 7: N/C
- PIN 8: N/C

### STYLE 2

- PIN 1: N/C
- PIN 2: Vx
- PIN 3: GND
- PIN 4: Vout
- PIN 5: N/C
- PIN 6: N/C
- PIN 7: N/C
- PIN 8: N/C

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### MECHANICAL OUTLINE

- TITLE: 8 LD SOP, GVP
- DOCUMENT NO: 98AS499302D
- REV: C
- CASE NUMBER: 1368-01
- 18 DEC 2008
- STANDARD: NON-JEDEC

## CASE 1368-01

### ISSUE C

SMALL OUTLINE PACKAGE

MP3V5010

Freescale Semiconductor
PACKAGE DIMENSIONS

NOTES:
1. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 (0.152) PER SIDE.
4. DIMENSION "D" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.008 (0.203) MAXIMUM.

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<td>0.008 – 0.042</td>
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</tr>
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CASE 1369-01
ISSUE O
SMALL OUTLINE PACKAGE
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